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Technical data KEBAFORM C 902 XFA

POM copolymer, non-reinforced, medium viscosity, UV-stabilized, very low formaldehyde emission (< 1 ppm according to VDA 275) for applications in vehicle interiors. Formaldehyde emission remains very low (< 2 ppm according to VDA 275) even under unfavorable processing conditions (e.g. high melt temperature) or when colored.

Polymer: POM

ISO designation: POM-C

Productgroup: POM

Brief description of the product family:

Under the trade name KEBAFORM, we market a wide product range of POM copolymers. KEBAFORM products are characterized by high strength and surface hardness, excellent chemical resistance and outstanding sliding and wear behavior. The product range includes basic grades with different viscosities, sliding and wear-optimized grades, variants reinforced with glass and carbon fibers, and various other modified compounds.

Properties:

dimensionally stable, low-emission, good chemical resistance, good gliding properties, High strength, High wear resistance, High weather resistance, semi-crystalline

Typical areas of application:

Industries:

Physical properties	
Water absorption in % in Anlehnung an ISO 62	0.22
Density in kg/m³ ISO 1183-1	1410.00

Mechanical properties	
E-modulus in MPa ISO 527-1	2700
Yield stress in MPa ISO 527-1	60
Elongation at yield in % ISO 527-1	11.0
Elongation at break in % ISO 527-1	40.0
Impact strength (Charpy) at 23°C in kJ/m ² ISO 179-1eU	100.0
Notched impact strength (Charpy) at 23°C in kJ/m ² ISO 179-1eA	7.0

Rheological properties	
Melt flow rate MFR (test condition)	190°C / 2,16kg
Melt flow rate MFR in g/10min ISO 1133	9.0
Shrinkage in flow direction in % ISO 294-4	2.00

Rheological properties

Shrinkage transverse to the flow direction in % | ISO 294-4

Thermal properties	
Melting temperature (DSC, 10°C/min) in °C ISO 11357-1/-3	170.0
Heat deflection temperature HDT (1.80 MPa) in °C ISO 75-1/-2	93.0
Coefficient of thermal expansion in flow direction in E-6/K ISO 11359-1/-2	120.0
Coefficient of thermal expansion transverse to the flow direction in E-6/K ISO 11359-1/-2	120.0
Fire behavior (0.4 mm wall thickness) IEC 60695-11-10	НВ
Fire behavior (0.8 mm wall thickness) IEC 60695-11-10	НВ
Fire behavior (1.6 mm wall thickness) IEC 60695-11-10	НВ
Fire behavior (3.2 mm wall thickness) IEC 60695-11-10	НВ

Electrical properties	
Contact resistance in Ohm*m IEC 60093	1e+16
Surface resistivity in ohms IEC 60093	1e+16

Electrical properties

Dielectric strength in kV/mm | IEC 60243-1

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Processing instructions: Pre-drying:

Dryer type: dry air dryer. Temperature: 80 – 100°C Drying time: 2 – 4 h

Temperatures:

Melt temperature: 180 – 210°C Mold temperature: 60 – 120°C (general guideline for technical parts: min. 90°C) Back pressure (spec.): 10 – 40 bar Injection speed: medium Injection pressure: 600 – 1200 bar (depending on part and gate geometry) Holding pressure: 600 – 1200 bar (depending on part and gate geometry)

General processing instructions:

The residence time of the melt in the screw antechamber should be kept as short as possible. In case of longer downtimes, an empty spraying of barrel and hot runner is necessary.

Legal notices:

The information in this data sheet is based on our current knowledge and experience. Due to the wide range of possible influences during processing and application of our products, they do not exempt the processor from carrying out his own tests and trials. A legally binding assurance of certain properties or suitability for a specific application cannot be derived from our information.

* FE products are development products which are still in the trial phase. Technical data may still change in the course of product and process development. No final decision has yet been made on the commercialization of FE products. We reserve the right to discontinue the manufacture of FE products without giving further reasons.

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